AFX and DFX materials can be overmolded, injection molded, or adhesively bonded. These guidelines are suggestions for a starting point. Each application may vary, and it is recommended to test prior to production.

- **ADHESIVE BONDING:**
  - Both surfaces should be clean and dry; a light wipe with isopropyl alcohol (IPA) is effective. Avoid aggressive scrubbing and/or more aggressive cleaning agents as they can damage the material. If necessary, a mild abrasive, such as a Scotch-Brite pad, can be used to lightly scratch the surface to improve bonding.

- **INJECTION / OVERMOLDING:**
  - Temperature and time under pressure can affect material characteristics. Maximum continuous processing temperature of 180°C is recommended; however, this can be exceeded for short periods of time. (For example, at 180°C and 5 PSI, processing time should be 25-30 seconds max. If PSI was higher, the processing time would need to be significantly shorter.)
  - Because time, temperature, and pressure can vary during the process it is recommended to run trials with specific processing settings. Several conditions are noted below that have been used successfully.

  - **EVA COMPRESSION MOLDING**
    - Foaming agent: Azodicarbonamide
    - Pressure inside mold: ~ 500 KPa
    - Molding temperature: 140°C – 160°C
    - Part temperature after cooling: 30°C – 40°C
    - Cycle time: 13 – 15 Minutes (Heating & Cooling)
    - Primers and Adhesives: Mix of Ethyl Acetate, Methyl Ethyl Ketone, Acetone (MEK and Acetone are the volatile, organic solvents.)

  - **TPU INJECTION MOLDING**
    - Injection pressure: ~ 80 MPa
    - Holding pressure: ~ 100 MPa
    - Molding temperature: 180°C – 220°C
    - Part temperature after cooling: 50°C – 90°C
    - Cycle time: 1 minute

NOTE: The conditions stated are a starting point. Actual conditions will vary based on materials, adhesives used and other factors. We strongly recommend the process be tested before production is started.